

ATTORNEY DOCKET NO.: CHITTIPEDDI 59-108



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of: Sailish Chittipeddi, *et al.*

Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

Commissioner for Patents
Washington, D.C. 20231

PATENT
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CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on <u>11/14/2002</u> (Date)	
<u>EDITH SHEK</u> (Printed or typed name of person signing the certificate)	
<u>Edith Shek</u> (Signature of the person signing the certificate)	

Sir:

AMENDMENT UNDER 37 C.F.R. § 1.111

In response to the Office Action mailed August 26, 2002, please amend the above-identified Application as follows:

IN THE CLAIMS:

Please amend Claim 1 as follows:

Sbd 1. (Three Times Amended) A wire bonding method, comprising the steps of:

forming a semiconductor substrate with a copper (Cu) interconnect material;